Product End-of-Life Disassembly Instructions

Product Category: External Options Monitor and Display

Marketing Name / Model
[List multiple models if applicable.]

Name/Model: HP Giraffe P274 Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm power BD interface BD</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain _____</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Indicates background illuminated displays with gas discharge lamps panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC power cord, HD cable, HDMI cable, VGA cable</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(HEX HEAD)</td>
<td></td>
</tr>
<tr>
<td>Description #4 SPANNER</td>
<td>#10</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Cable From Display Head
2. Remove Stand Base From Display Head
3. Remove Rear Cover From Display Head
4. Remove Adhesive From Display Head
5. Remove Bracket From Display Head
6. Remove Middle Frame From Display Head
7. Middle Frame ASSY Disassembly
8. Rear Cover ASSY Disassembly
9. Bracket ASSY Disassembly
10. Stand ASSY Disassembly
11. Base ASSY Disassembly
12. Panel Module Disassembly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
P274 Disassemble Process

Prepare By: Jess Yang
Date : 2018/12/07
1. Remove cable from display head
2. Remove Stand Base From Display Head

2. Push the red point

3. Remove stand base assembly
3. Remove Rear Cover From Display Head

4. Release the six screws from rear cover by cross screwdriver

5. Pull up rear cover left and right side
3. Remove Rear Cover From Display Head

6. Pull the rear cover from the bottom up

7. Remove rear cover
4. Remove Adhesive From Display Head

8. Remove aluminum foil

9. Remove acetate tape
5. Remove Bracket From Display Head

10. Release the two screws from bracket by cross screwdriver

11. Overturn bracket and remove all cables
6. Remove Middle Frame From Display Head

12. Remove bracket assembly and release the thirteen screws from middle frame

13. Remove middle frame from the top down
14. Destroy heat stake then remove OSD key and lens
8. Rear Cover ASSY Disassembly

15. Destroy heat stake then remove the small iron
9. Bracket ASSY Disassembly

16. Remove the black mylar

17. Release the five screws by cross screwdriver

18. Release the four screws by cross screwdriver

19. Remove PCB then tear off gasket and white mylar
10. Stand ASSY Disassembly

20. Push the release button then remove the stand

21. Release the four screws by cross screwdriver

22. Remove hinge from stand

23. Release four screws from hinge
10. Stand ASSD Disassembly

24. Release the two screws and nut from hinge by cross screwdriver

25. Remove all part
11. Base ASSY Disassembly

26. Remove the five rubbers then release all screws by cross screwdriver

27. Remove the chassis
Panel Module Disassembly

1. Back side fixed tape disassembly
   - Use your fingers to tear off the tape and place it on the back

2. Back side Shielding disassembly
   - Use cross screwdriver to unlock the two screws

3. Back side Source board disassembly
   - Lift up the source board that stick by double tape

Disassemble panel assembly
12. Panel Module Disassembly

04. Front side OC disassembly

Note: There will be residual gum on the OC and MF. It is easy to tear off by hands (see next page).

06. Take out 3pcs film

Note: Use hand to carry the suspension loop left and right side to take out the film.

Film

residual gum on OC

residual gum on MF

5. Front side middle frame disassembly

Loose all the hooks by hand.
12. Panel Module Disassembly

07. Take out LGP
- Note: use hand to hold the two sides when taking out LGP
- Use tape to stick one bottom corner of the LGP, then take it out.

08. Take out reflector
- Use tape to stick one bottom corner of the reflector plate, then take it out.

09. Take out light bar
- Use knife to separate light bar and RC, then take out light bar.
- Note: Light bar can't be reused after taking it out.
Thank You !!!